

668LF BOM-style material declaration. BI Technologies Corporation

9/15/2010

No content here is banned per E.U. R.o.H.S.. Average mass of 668LF thin film network is 0.15 grams each. Prepared by Eric Arnold (714) 447-2565
Weights above 1 milligram rounded to the nearest mg. Values less than 1 milligram given in scientific notation.

Sub-component	Material	% of total mass	Substance name	CAS #	Substance Weight (grams)	Special classification
Die	substrate	5.42%	Al2O3	1344-28-1	0.008	
			CaO	1305-78-8	2.09E-06	
			FeO2	1345-25-1	4.19E-06	
			MgO	1309-48-4	2.09E-06	
			MnO2	1313-13-9	8.37E-06	
			SiO2, amorphous	7631-86-9	1.26E-05	
			TiO2	13463-67-7	4.19E-06	
	nichrome resistor	0.0003%	NiCrOx	combination of 7440-02-0, 7440-47-3, & 1308-38-9	4.30E-07	
			nickel barrier	Ni	7440-02-0	6.72E-07
	gold conductor	0.01%	Au	7440-57-5	1.45E-05	
			BCB passivation	dvs-BCB, divinylsiloxane-bis-benzocyclobutene	124221-30-3	1.38E-05
Leadframe	copper alloy	37.1%	Cu	7440-50-8	0.056	
			Fe	7439-89-6	0.001	
			P	7723-14-0	1.71E-05	
			Zn	7440-66-6	6.84E-05	
	matte Sn plating silver plating	1.6% 0.9%	Sn	7440-31-5	0.001	
			Ag	7440-22-4	0.001	
			Die adhesive	conductive epoxy	0.9%	Ag
Wire bonds	gold	0.09%	trade secret	unknown	2.73E-04	non-hazardous
			Au	7440-57-5	1.34E-04	
Molding compound	filled epoxy	53.9%	carbon black	1333-86-4	4.16E-04	
			epoxy resin, cresol novolac	29690-82-2	0.002	
			SiO2, fused silica	60676-86-0	0.073	
			trade secret	unknown	0.008	non-hazardous
			Ink marking	epoxy	0.04%	trade secret